

1N4148WS-Q1

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1N4148WS-Q1

150mA Surface Mount Switching Diode-100V

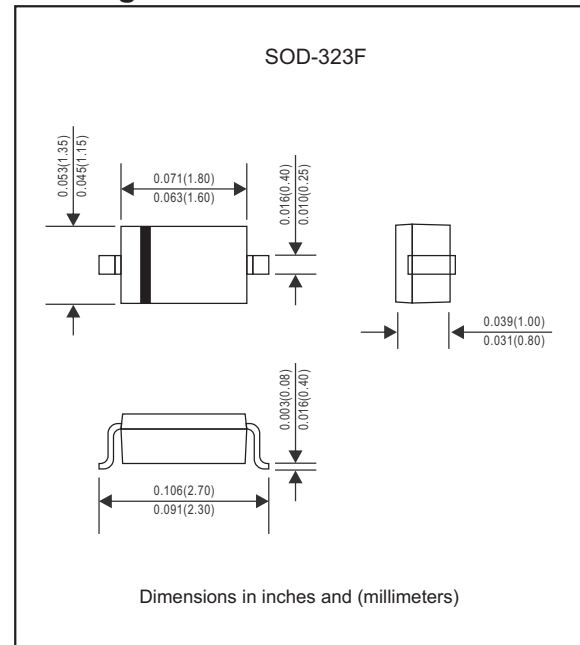
Features

- Fast switching speed
- Surface mount package ideally suited for automatic insertion
- Tiny plastic SMD package
- High conductance
- Silicon epitaxial planar chip
- Lead-free parts meet RoHS requirements
- Qualified to AEC-Q101 standards for high reliability
- Suffix "-H" indicates Halogen free part, ex. 1N4148WS-Q1-H

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-323F
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.005 gram

Package Outline



Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	Symbol	1N4148WS-Q1	UNIT
Maximum reverse voltage	V_R	75	V
Maximum peak reverse voltage	V_{RM}	100	V
Maximum RMS voltage	V_{RMS}	53	V
Maximum DC blocking voltage	V_{DC}	75	V
Maximum average forward current at $T_A = 25^\circ\text{C}$	I_O	150	mA
Maximum peak forward surge current, 1.0us	I_{FSM}	2.0	A
Maximum power dissipation derate above 25°C	P_D	200	mW
Maximum capacitance between terminals (Notes 1)	C_T	2.0	pF
Maximum reverse recovery time (Notes 2)	t_{rr}	4.0	ns
Thermal resistance junction to ambient	$R_{\theta JA}$	625	$^\circ\text{C/W}$
Operating junction temperature range	T_J	-55 to +150	$^\circ\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	Symbol	Max.	UNIT
Maximum instantaneous forward voltage $I_F=0.001\text{A}, T_J = 25^\circ\text{C}$ $I_F=0.01\text{A}, T_J = 25^\circ\text{C}$ $I_F=0.05\text{A}, T_J = 25^\circ\text{C}$ $I_F=0.15\text{A}, T_J = 25^\circ\text{C}$	V_F	0.715 0.855 1.000 1.250	V
Maximum reverse leakage current $V_R=20\text{V}, T_J = 25^\circ\text{C}$ $V_R=75\text{V}, T_J = 25^\circ\text{C}$	I_R	0.025 1.000	μA

Notes 1: $V_R=0\text{V}, f=1\text{MHz}$

2: $I_F=I_R=10\text{mA}$ $I_{rr}=0.1 \times I_R$, $R_L=100\Omega$

Rating and characteristic curves (1N4148WS-Q1)

Fig. 1 TYPICAL FORWARD CHARACTERISTICS

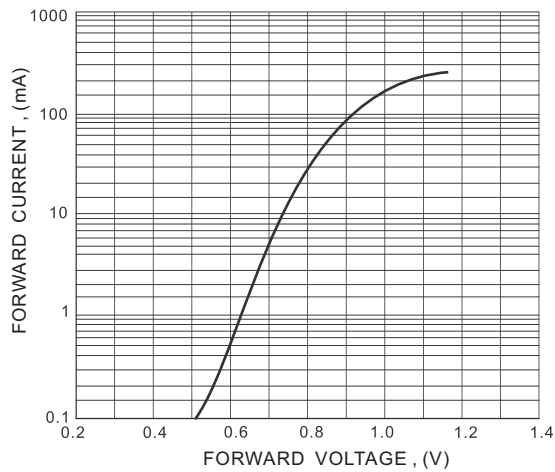


Fig. 2 TYPICAL REVERSE CHARACTERISTICS

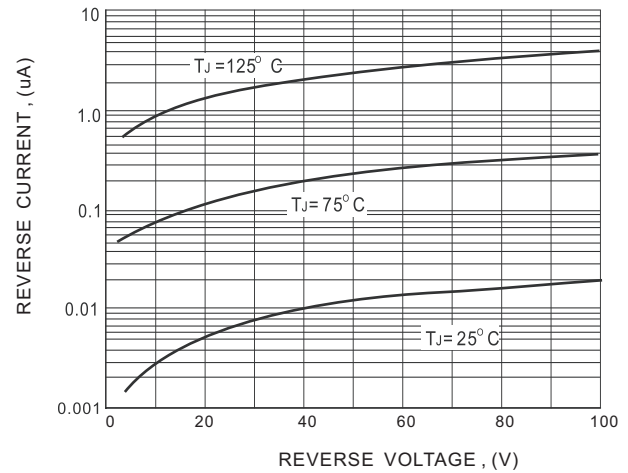
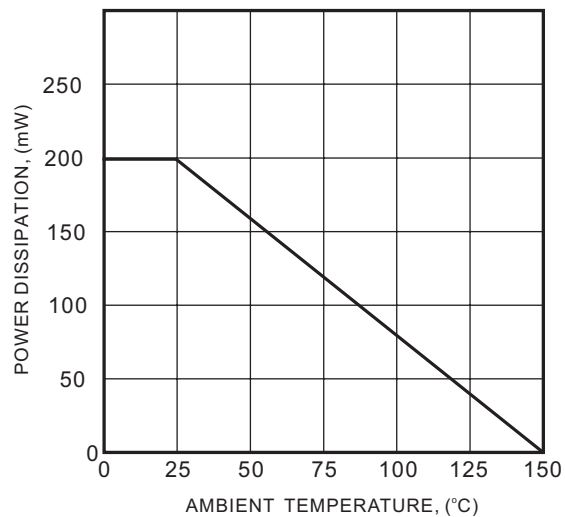


Fig. 3 POWER DERATING CURVE



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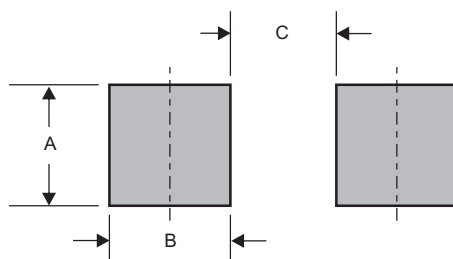
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
1N4148WS-Q1	5D

Suggested solder pad layout

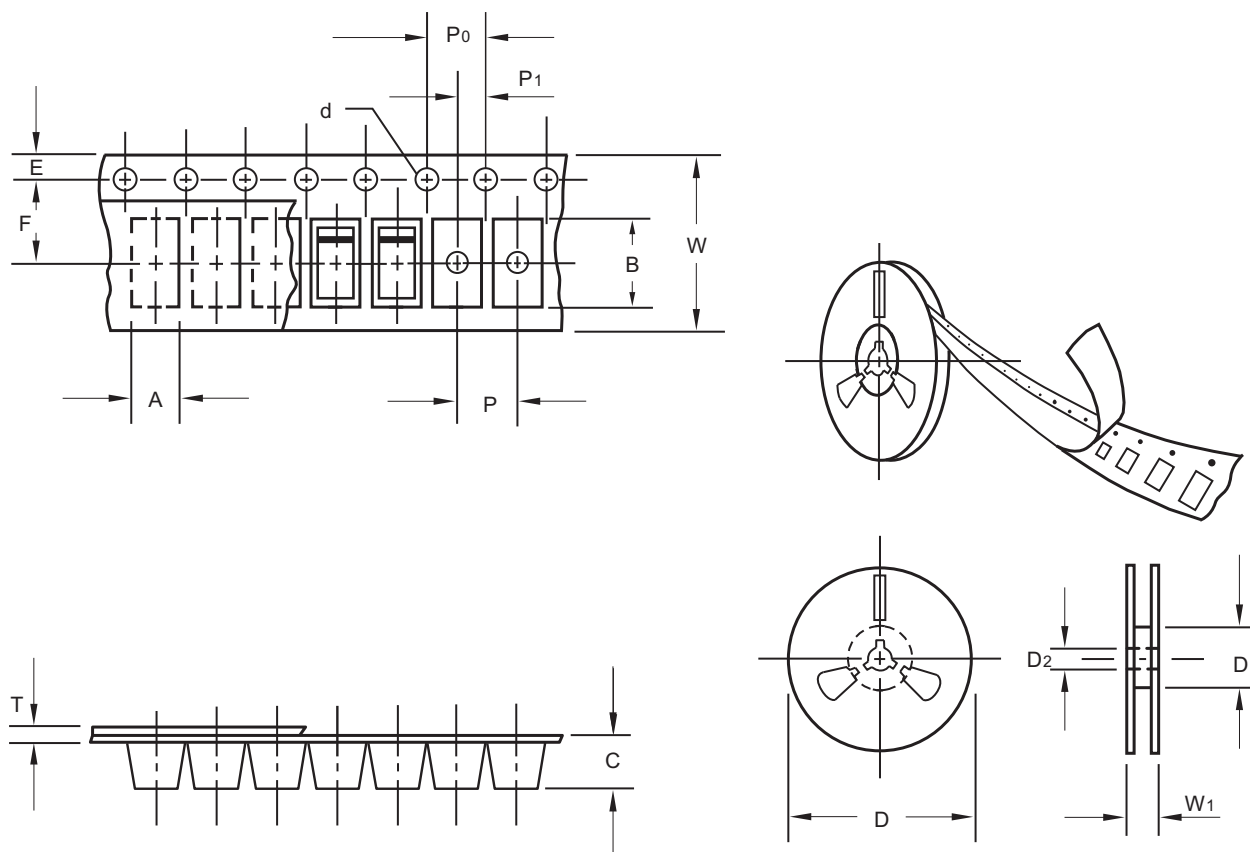


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-323F	0.033 (0.83)	0.025 (0.63)	0.063 (1.60)

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Packing information



unit:mm

Item	Symbol	Tolerance	SOD-323F
Carrier width	A	0.1	1.48
Carrier length	B	0.1	3.30
Carrier depth	C	0.1	1.25
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	54.40
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

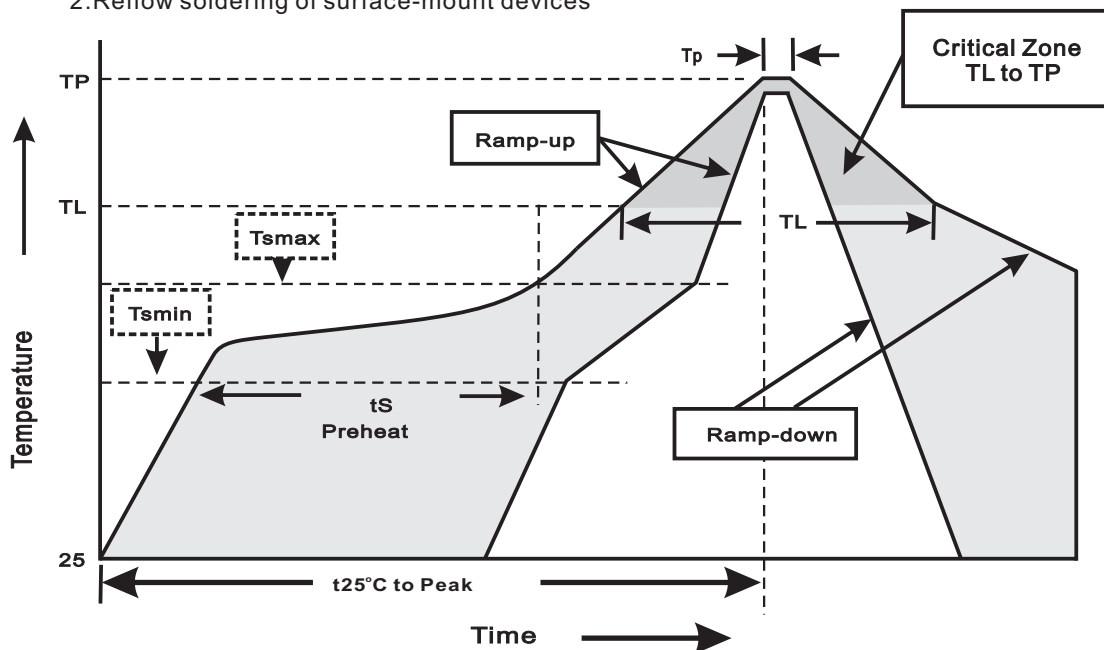
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-323F	7"	3,000	4.0	30,000	183*123*183	178	382*257*387	240,000	8.0

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	$<3^{\circ}\text{C}/\text{sec}$
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(min to max)(t_s)	150°C 200°C 60~120sec
T_{smax} to T_L -Ramp-upRate	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	$<6\text{minutes}$

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High reliability test capabilities

Item Test	Conditions	Reference
1. MSL Preconditioning	24hr bake@125°C+168hrs@85°C /85%RH+3xIR@260°C+1flux immersion+alcohol+DI H2O rinse	JESD22-A113
2. Operation Life	Ta=25°C, Rated Current (Io=Io max.) Test Duration: 1000hrs	MIL-STD-750E METHOD 1027.3
3. High Temperature Reverse Bias	80% Rated VR (Tj=Tj max.) Test Duration: 1000hrs	JESD22-A108
4. High Temperature Storage Life	Ta=125°C Test Duration: 1000hrs	JESD22 A-103
5. Temperature Cycle	-55°C(15min) to 150°C(15min) Test Cycles: 1000cycles	JESD22 A-104
6. Autoclave	P=2atm Ta=121°C RH=100% Test Duration: 96hrs	JESD22 A-102
7. Intermittent Operational Life	Ta=25°C, On/lo Max. 2min, Off/2min, Test Cycles: 15000cycles	MIL-STD-750E METHOD 1037
8. Solderability	245±5°C for 5sec	J-STD-002
9. Moisture Resistance	Ta=85°C/85% Relative humidity Test Duration: 1000hrs	MIL-STD-750E METHOD 1021.2
10. Resistance To Solder Heat	260±5°C for 10sec	JESD22 B-106
11. High Temperature High Humidity Reverse Bias	Ta=85°C, 85%RH, with device reverse biased at 80% of rated breakdown voltage up to a maximum of 100V or limit of chamber Test Duration: 1000hrs	JESD22-A101